

AMENDMENT TO THE CLAIMS:

The following claim set replaces all prior versions, and listings, of claims in the application:

1. (currently amended) A method for producing a resin composition pellet from a comprised of a resin (A) and a fibrous filler (B), the method comprising: in which a weight average fiber length (L) of a fibrous filler (B) is 180 to 360 μm , comprising
 - (a) supplying to an extruder an amount of 55 to 80% to 55% by weight of feed pellets comprised of the resin (A) and 20 to 45% by weight of the fibrous filler (B), the fibrous filler (B) having with a weight average fiber length (L) of 1 mm or more based on the (herein, a total weight of the resin (A) and the fibrous filler (B), is 100% by weight) to an extruder, wherein the step of supplying the resin (A) and the fibrous filler (B) to the extruder includes:
 - (i) supplying one [[a]] part containing [[of]] an amount (x) of the feed pellets comprised of the resin (A) is supplied through a main feed port of the extruder; and
 - (ii) supplying the fibrous filler (B) and a remaining part amount (1-x) of the feed pellets comprised of the resin (A) containing an amount (1-x) are supplied through a side-feed port provided downstream of the main feed port backward in an extrusion direction of the extruder from the main feed port so that a weight ratio of x/(1-x) is becomes 50/50 to 10/90% by weight
 - (b) melt-blending the one and another parts of the resin (A) with the fibrous filler (B) within the extruder to achieve a weight average fiber length (L) of the fibrous filler (B) of 180 to 360 μm based on the total weight of the resin (A) and the fibrous filler (B), and thereafter
 - (c) forming a pellet of the melt-blended resin (A) and the fibrous filler (B).
2. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein 5 to 40% by weight a proportion of the fibrous

filler (B) in the pellet has [[with]] a fiber length exceeding 300 μm in the resin composition pellet is 5 to 40% by weight.

3. (currently amended) A method for producing a resin composition pellet according to claim 1, comprising melt-blending the resin (A) and the fibrous filler (B) in a wherein the resin composition pellet is obtained by one-pass treatment [[with]] through the extruder.
4. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein the resin (A) comprises a liquid crystalline polymer.
5. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein the fibrous filler (B) comprises at least one filler selected from the group consisting of [[a]] glass fibers fiber and [[a]] carbon fiber fibers.
6. (canceled)
7. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein the extruder comprises a twin-screw extruder having a plasticizing zone, a kneading zone, and a ratio (L/D) between [[a]] screw length (L) and [[a]] screw diameter (D) of (L/D) is 20 or more, a screw has a plasticizing zone and a kneading zone, and wherein the side-feed port is positioned on a downstream side of the plasticizing zone.
8. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein the a melt viscosity of the resin composition pellet [[is]] has a melt viscosity of 10 to 55 Pa•s.
9. (currently amended) A method for producing a An injection-molded product made by producing a resin composition pellet according to claim 1, and thereafter injection molding the resin composition pellet to produce an

injection-molded product therefrom, wherein [[a]] the injection-molded product obtained by molding a resin composition pellet by injection has a flexural modulus of 15,000 MPa or more, a flatness before solder reflow treatment of 0.09 mm or less, and a difference in flatness before and after heating corresponding to the solder reflow treatment at a peak temperature of 230 to 280⁰C of 0.02 mm or less.

10. (new) An injection-molded product according to claim 9 in the form of a planar socket for a semiconductor device, wherein the planar socket has a height of 5.0 mm or less and includes a lattice area provided with a number of pin holes, the lattice area having a thickness of 0.5 mm or less and a pitch interval of 2.0 mm or less.